瀚荃股份有限公司
CviLux Corporation

ENGINEERING DEPT.	PRODUCT SPECIFICATION For CS05 Series Connector System	SPEC.NO.: SPCS005D PAGE: 1 / 3

1. SCOPE:
   This specification contains the test requirement of subject DIP socket when tested under the condition and below standards base on CviLux test procedure

2. APPLICABLE STANDARDS:
   MIL - STD - 202 Methods for test of connectors for electronic equipment
   MIL - STD - 1344 Test methods for electrical connectors

3. APPLICABLE SERIES NO.: CS05 Series

4. SHAPE, CONSTRUCTION AND DIMENSIONS
   See attached drawings

5. MATERIALS
   See attached drawings

6. ACCOMMODATED P.C.BOARD
   6.1 Thickness: 1.6 mm (.063″)
   6.2 P.C. Board Layout: See attached drawings

CVILUX CORP.
2001.12.19
ISSUED

REVIEWED : Alex APPROVED : David VERIFIED : Rita .

7. ELECTRICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
7.1	Rated current and voltage		1A 250V AC (r.m.s.)
7.2	Contact resistance	Dry circuit of DC 20 mV max. , 100 mA max.	Less than 20 mΩ
7.3	Dielectric strength	When applied AC 1000 V 1minute between adjacent terminal	No change
7.4	Insulation resistance	When applied DC 500 V between adjacent terminal or ground	More than 1000 MΩ

8. MECHANICAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
8.1	Pin retention force	Push pin from insulator base at speed 25±3 mm per minute	More than 400 gram
8.2	Single contact insertion force	Mating speed 25 mm/minute Force with 0.33 × 0.51 mm test pin	300 gram max.
8.3	Single contact withdrawal force	Unmating speed 25 mm/minute Force with 0.20 × 0.38 mm test pin	30 gram min.
8.4	Durability	Connector shall be subject to 50 cycles of insertion and withdrawal	Contact resistance: Less than twice of initial

9. ENVIRONMENTAL PERFORMANCE:

	ITEM	TEST CONDITION	REQUIREMENT
9.1	Temperature rise	Then carried the rated current	30°C max.
9.2	Vibration	1.5 mm 10-55-10 HZ/minute each 2 hours for X,Y and Z directions	Appearance: No damage Discontinuity: 1 micro second max.
9.3	Solderability	Soldering time: 5 ± 0.5 second Soldering pot: 230 ± 5°C	Minimum: 90% of immersed area
9.4	Resistance to soldering heat	Soldering time: 5 ± 0.5 second Soldering pot: 260 ± 5°C	No damage
9.5	Heat aging	105 ± 2°C, 96 hours	No damage
9.6	Humidity	40 ± 2°C, 90-95% RH, 96 hours measurement must be taken within 30 min. after tested	Appearance: No damage Contact resistance: Less than twice of initial Dielectric strength: To pass para 7-3

	ITEM	TEST CONDITION	REQUIREMENT
9.7	Temperature cycling	One cycle consists of : (1)-55$^{+0}_{-3}$ °C , 30 min. (2)Room temp. 10-15 min. (3) 85$^{+3}_{-0}$ °C , 30 min. (4)Room temp. 10-15 min.	Appearance: No damage Contact resistance: Less than twice of initial
9.8	Salt spray	Temperature: 35±3°C Solution: 5±1% Spray time: 48±4 hours Measurement must be taken after water rinse	Appearance: No damage Contact resistance: Less than twice of initial

10. AMBIENT TEMPERATURE RANGE: -40 to + 105°C